

**COMPOSITE LAMINATE CIRCUIT STRUCTURE AND  
METHODS OF FABRICATING**

**ABSTRACT OF DISCLOSURE**

A laminate circuit structure assembly is provided that ~~comprises~~ at least two modularized circuitized voltage plane subassemblies; optionally an interposer located between each of the subassemblies and wherein the subassemblies and interposer, if present, are bonded together with a cured dielectric coating. The interposer ~~comprises~~ dielectric layers disposed about an internal electrically conductive layer.